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1. Name of conveying party(ies):

Commissioner of Patents and Tradema

Tadatomo SUGA Toshihiro ITO Akira YAMAUCHI

Additional name(s) attached? ☐ Yes ■ No

3. Nature of conveyance:

Assignment

☐ Merger

☐ Security Agreement

☐ Change of Name

☐ Other:

Execution Date: March 14, 2005

2. Name and address of receiving party(ies):

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Additional names/addresses attached? ☐ Yes ■ No

PATENT REEL: 016993 FRAME: 0702

10/528690 JOI2 Regis Point 22 MAR 2005

1.	Application number(s) or patent number(s): If this document is being filed with a new application, the A. Patent Application No.(s):		execution date of the application is: March 22, 2005 B. Patent No.(s):					
	Additional numbers attached? ☐ Yes ■ No	,						
ō.	Name/address of party to whom correspondence concerning document should be mailed:	6.	То	tal number o	f applications/patents involved: 1			
	Randolph A. Smith	7.	To	Authorized Authorized	FR 1.21(h) & 3.41): \$40 to be charged by credit card to be charged to deposit account			
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	Randolph A. Smith Name of Person Signing Signature Signature	ist 32,	- 548	March Date	<u>n 22, 2005</u>			

Total number of pages including cover sheet, attachments, and document: 5

PATENT REEL: 016993 FRAME: 0703

ASSIGNMENT

For good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, the undersigned hereby assign(s), transfer(s) and set(s) over to:

- (1)Tadatomo SUGA
- (2) TORAY ENGINEERING CO., LTD.
- (3) OKI ELECTRIC INDUSTRY CO., LTD.
- (4) SANYO ELECTRIC CO., LTD.
- (5) SHARP KABUSHIKI KAISHA
- (6) SONY CORPORATION
- (7) KABUSHIKI KAISHA TOSHIBA
- (8) FUJITSU LIMITED
- (9) MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD.
- (10) ROHM CO., LTD.
- (11) RENESAS TECHNOLOGY CORP.

having respective addresses:

- (1) c/o The University of Tokyo, School of Engineering, 7-3-1, Hongo, Bunkyo-ku, Tokyo, 113-8656 Japan
- (2) Nakanoshima Mitsui Bldg., 3-3, Nakanoshima 3-chome, Kita-ku, Osaka-shi, Osaka, 530-8222 Japan
 - (3) 7-12, Toranomon 1-chome, Minato-ku, Tokyo, 105-8460 Japan
 - (4) 5-5, Keihanhondori 2-chome, Moriguchi-shi, Osaka, 570-8677 Japan
 - (5) 22-22, Nagaikecho, Abeno-ku, Osaka-shi, Osaka, 545-8522 Japan
 - (6) 7-35, Kitashinagawa 6-chome, Shinagawa-ku, Tokyo, 141-0001 Japan
 - (7) 1-1, Shibaura 1-chome, Minato-ku, Tokyo, 105-8001 Japan
 - (8) 1-1, Kamikodanaka 4-chome, Nakahara-ku, Kawasaki-shi, Kanagawa, 211-8588 Japan
 - (9) 1006, Oaza Kadoma, Kadoma-shi, Osaka, 571-8501 Japan
 - (10) 21, Mizosakicho, Saiin, Ukyo-ku, Kyoto-shi, Kyoto, 615-8585 Japan
 - (11) 2-4-1, Marunouchi, Chiyoda-ku, Tokyo, 100-6334 Japan

(hereinafter collectively designated as the "ASSIGNEE"), its successors and assigns, the entire right, title, and interest for the United States in the invention, and all applications for patent and any Letters Patent which may be granted therefor, including said application, and all United States Letters Patents which may be granted therefore, and all divisions, reissues, continuations and extensions thereof, the said interest being the entire ownership of said Letters Patent when granted to be held by said ASSIGNEE, its successors, assigns or their legal representatives, to the full end of the term for which said Letters Patent may be granted, as fully and entirely as the same would have been and enjoyed by Assignor(s) if this assignment had not been made, the application being known by the Title:

BONDING DEVICE AND METHOD

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PATENT REEL: 016993 FRAME: 0704 for which the undersigned has/have executed an application for patent in the United States of America on the same day herewith. Where this instrument is not filed concurrently with the application, the following identifying information may be added after execution:

Serial No.

Filing Date: March 22, 2005

- 1. The undersigned hereby agree(s) to sign and execute any further documents and instruments which may be necessary, lawful and proper in the prosecution of said above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue application or in any amendments, extension of interference proceedings, or otherwise to secure the title thereto to the ASSIGNEE.
- 2. The undersigned agree(s) to execute all papers and documents and perform any act that may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.
- 3. The undersigned agree(s) to perform all affirmative acts that may be necessary to obtain a grant of a valid United States patent to the ASSIGNEE.
- 4. The undersigned hereby authorize(s) and request(s) the Commissioner of Patents and Trademarks in the United States to issue any and all Letters Patents resulting from said application or any division or divisions or continuing applications thereof to the said ASSIGNEE.
- 5. The undersigned hereby grant(s) to Randolph A. Smith and Smith Patent Office the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

March	14,	2005	
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Date

March 14, 2005

Date

Typed Name: Tadatomo SUGA

Typed Name: Toshihiro ITO

Page 2 of 3

March 14, 2005	Abra	Yamaniel	M
Date	Typed Name	Akira YAMA	AUCHI

This assignment may be signed before a U.S. Notary Public or before at least two witnesses who also sign here:

March 14, 2005

Date

Typed Name: Jiro TSUKAMOTO

March 14, 2005

Date

Typed Name: Hiroshi ARAI

RECORDED: 03/22/2005